LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1121IZ-3.3#TRPBF **(Engineering Calculation)** TO-92

TOTAL MASS (g): **0.2048082**

(printed on: 4/18/2011 10:01:11 PM)

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.001703**	**1000000**	**8315.097**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.088433	975000	431784.4
		Iron (Fe)	7439-89-6	0.002177	24000	10629.46
		Phosporus (P)	7723-14-0	2.7E-05	300	131.8307
		Zinc (Zn)	7440-66-6	6.3E-05	700	307.6049
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		**0.0907**	**1000000**	**442853.4**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.0056802	1000000	27734.24
		External Plating Total:		**0.0056802**	**1000000**	**27734.24**
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	0.00032	1000000	1562.437
		Internal Plating Total:		**0.00032**	**1000000**	**1562.437**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000617	750000	3012.574
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Resin (EP)		0.000206	250000	1005.819
		Die Attach Total:		**0.000823**	**1000000**	**4018.394**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.02532	240000	123627.9
		Bromine (Br)	40039-93-8	0.001055	10000	5151.161
		Silica (SiO2)	60676-86-0	0.07596	720000	370883.6
		Antimony Trioxide (Sb2O3)	1309-64-4	0.003165	30000	15453.48
		Metal Hydroxid		0	0	0
		Carbon Black (C)	1333-86-4	0	0	0
		Encapsulation Total:		**0.1055**	**1000000**	**515116.1**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**8.2E-05**	**1000000**	**400.3746**